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February 2009

FDS8842NZ

N-Channel PowerTrench® MOSFET

40 V, 14.9 A, 7.0 mΩ

Features

- Max $r_{DS(on)} = 7.0 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 14.9 \text{ A}$
- Max $r_{DS(on)}$ = 11.6 m Ω at V_{GS} = 4.5 V, I_D = 11.6 A
- HBM ESD protection level of 4.4 kV typical(note 3)
- High performance trench technology for extremely low r_{DS(on)} and fast switching
- High power and current handling capability
- Termination is Lead-free and RoHS Compliant

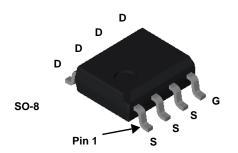
General Description

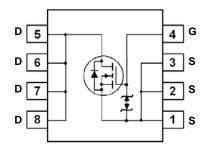
The FDS8842NZ has been designed to minimize losses in power conversion application. Advancements in both silicon and package technologies have been combined to offer the lowest $r_{DS(on)}$ while maintaining excellent switching performance.

Applications

- Synchronous Buck for Notebook Vcore and Server
- Notebook Battery
- Load Switch







MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V _{DS}	Drain to Source Voltage		40	V	
V _{GS}	Gate to Source Voltage			±20	V
1	Drain Current -Continuous			14.9	^
D	-Pulsed			93	_ A
E _{AS}	Single Pulse Avalanche Energy		(Note 4)	253	mJ
D	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	w
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1b)	1.0	VV
T _J , T _{STG}	Operating and Storage Junction Temper	erature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS8842NZ	FDS8842NZ	SO8	13 "	12 mm	2500 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25 °C		35		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 32 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.9	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25 °C		-6		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 14.9 \text{ A}$		5.6	7.0	
r _{DS(on)}	r _{DS(on)} Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 11.6 \text{ A}$		6.7	11.6	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 14.9 \text{ A}, T_J = 125 \text{ °C}$		8.9	11.1	
9 _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 14.9 A		111		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 45 V V 0 V	2890	3845	pF
Coss	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	340	455	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 101112	220	330	pF
R_g	Gate Resistance	f = 1 MHz	0.8		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		13	23	ns
t _r	Rise Time	V_{DD} = 20 V, I_D = 14.9 A, V_{GS} = 10 V, R_{GEN} = 6 Ω	7	14	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, K _{GEN} = 0 12	34	54	ns
t _f	Fall Time		5	10	ns
Q_g	Total Gate Charge	V _{GS} = 0 V to 10 V	52	73	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}$ $V_{DD} = 20 \text{ V},$ $I_{D} = 14.9 \text{ A}$	27	38	nC
Q _{gs}	Gate to Source Charge	I _D = 14.9 A	8.6		nC
Q_{gd}	Gate to Drain "Miller" Charge		9.7		nC

Drain-Source Diode Characteristics

V _{SD} Source to Drain Diode Forward Voltage	Source to Drain Diode, Forward Voltage	V _{GS} = 0 V, I _S = 14.9 A		0.8	1.2	V
	$V_{GS} = 0 V, I_{S} = 2.1 A$		0.7	1.2	V	
t _{rr}	Reverse Recovery Time	I _F = 14.9 A, di/dt = 100 A/μs		26	42	ns
Q _{rr}	Reverse Recovery Charge	T _F = 14.9 A, α/αt = 100 A/μs		15	27	nC

^{1.} R_{BJA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{BJC} is guaranteed by design while R_{BCA} is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



b) 125 °C/W when mounted on a minimum pad.

- 2. Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%. 3. The diode connected between the gate and source servers only as protection against ESD. No gate overvoltage rating is implied. 4. Starting T $_J$ = 25 °C, L = 3 mH, I $_{AS}$ = 13 A, V $_{DD}$ = 40 V, V $_{GS}$ = 10 V.

Typical Characteristics T_J = 25 °C unless otherwise noted

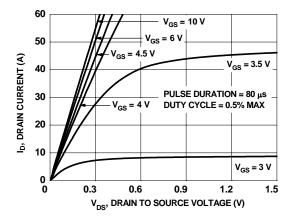


Figure 1. On-Region Characteristics

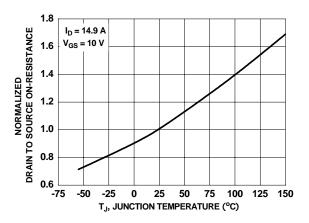


Figure 3. Normalized On-Resistance vs Junction Temperature

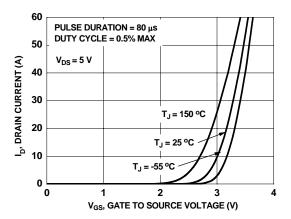


Figure 5. Transfer Characteristics

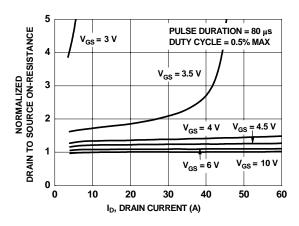


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

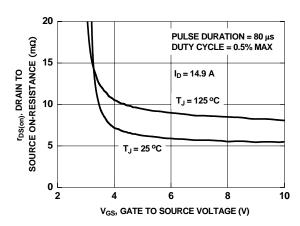


Figure 4. On-Resistance vs Gate to Source Voltage

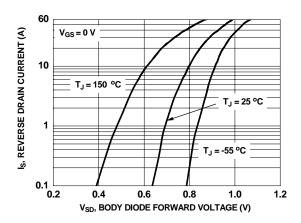


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted

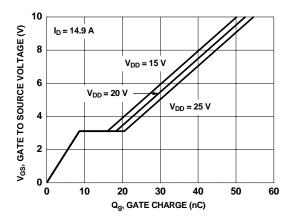


Figure 7. Gate Charge Characteristics

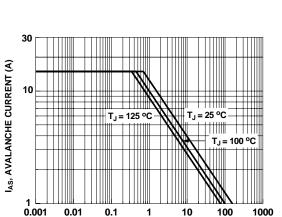


Figure 9. Unclamped Inductive Switching Capability

 ${\bf t}_{\rm AV}$, TIME IN AVALANCHE (ms)

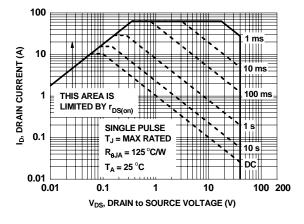


Figure 11. Forward Bias Safe Operating Area

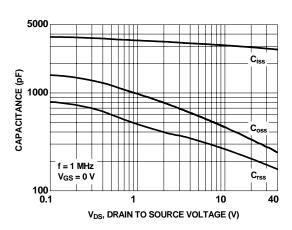


Figure 8. Capacitance vs Drain to Source Voltage

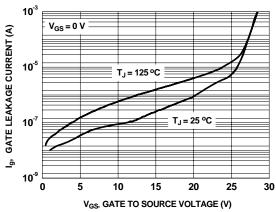


Figure 10. Igss vs Vgs

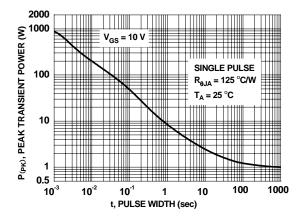


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted

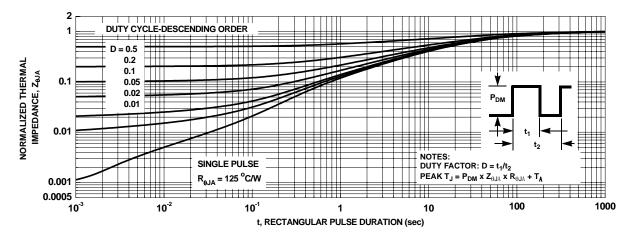


Figure 13. Transient Thermal Response Curve





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